

FIG. 1A

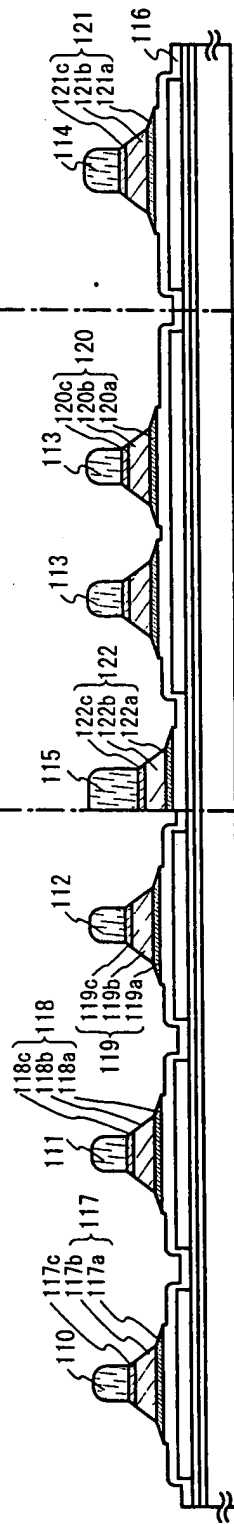


FIG. 1B

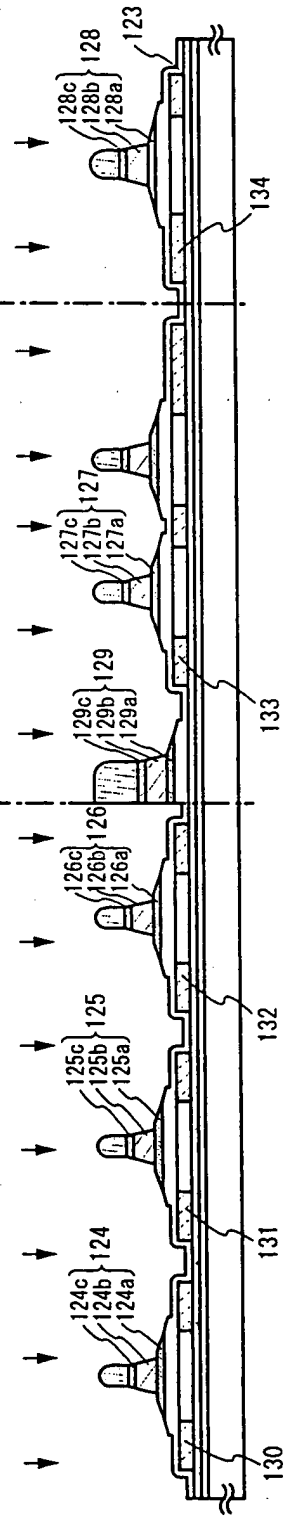
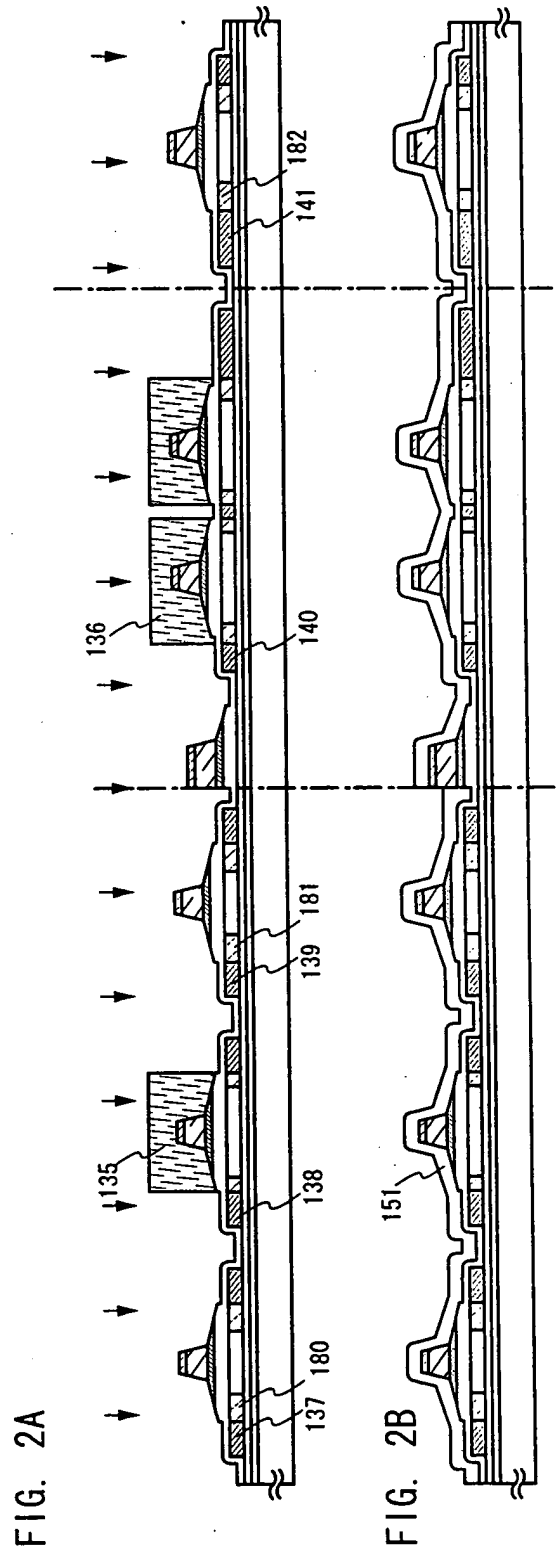


FIG. 1C



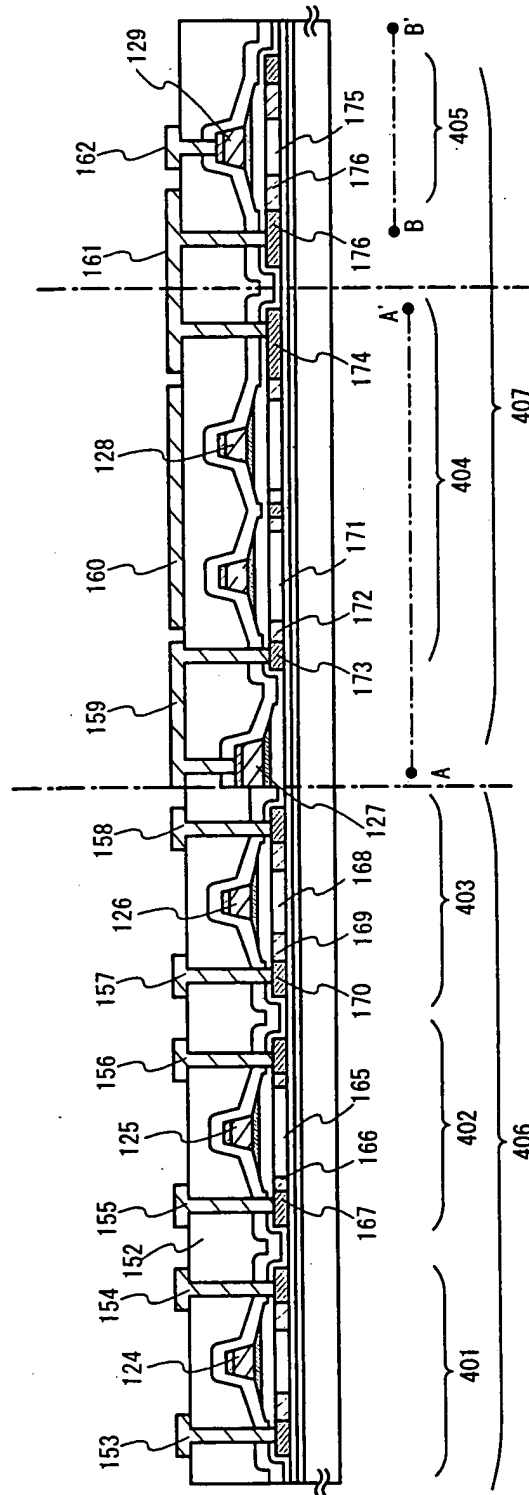


FIG. 3

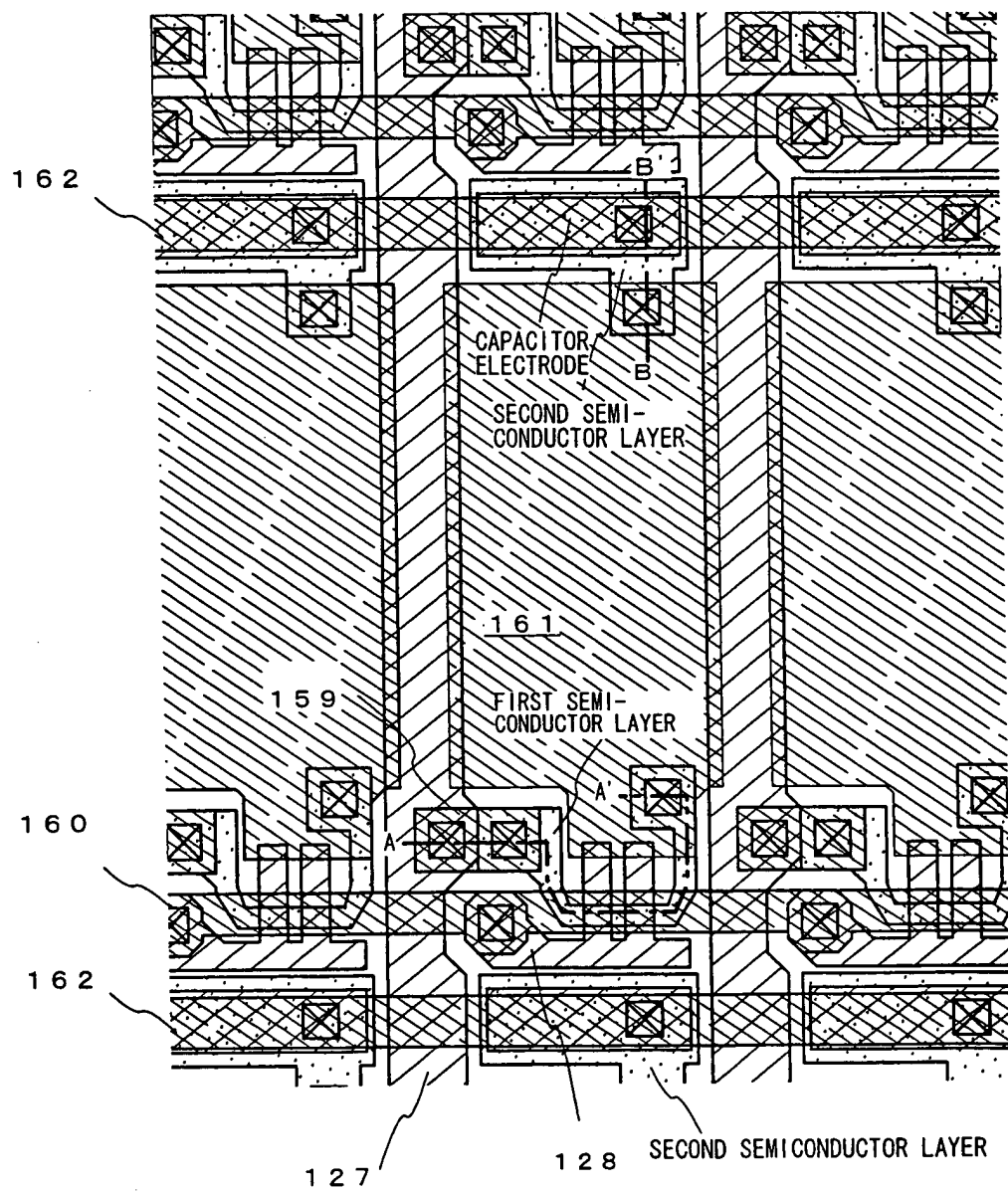


FIG. 4

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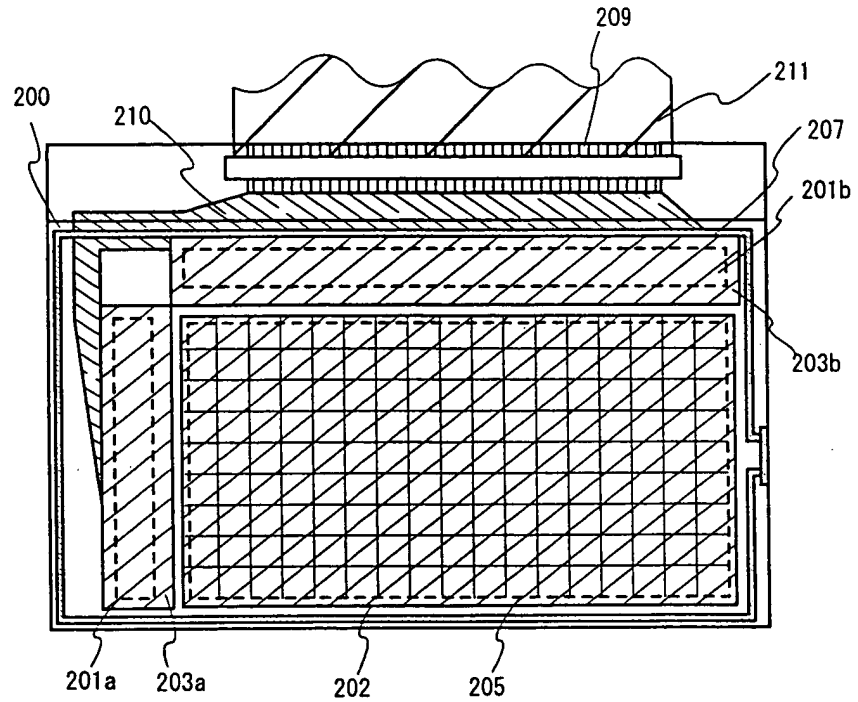
SEMICONDUCTOR DEVICE AND MANUFACTURING
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FIG. 5

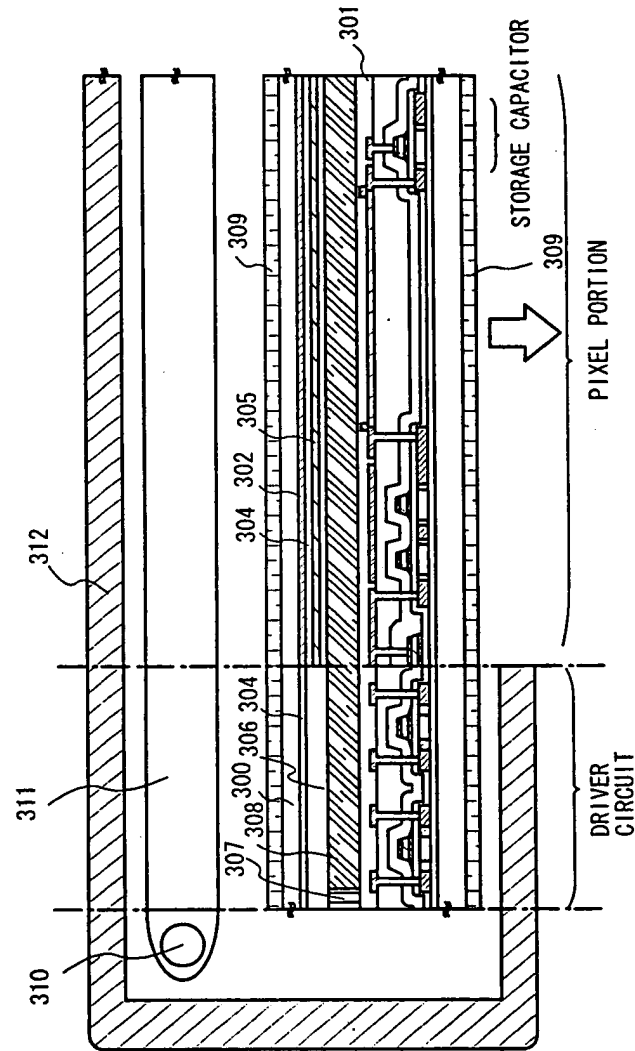


FIG. 6

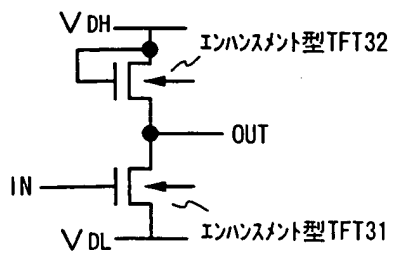


FIG. 7A

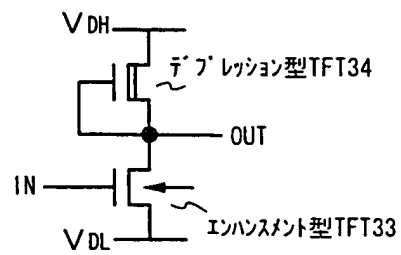


FIG. 7B

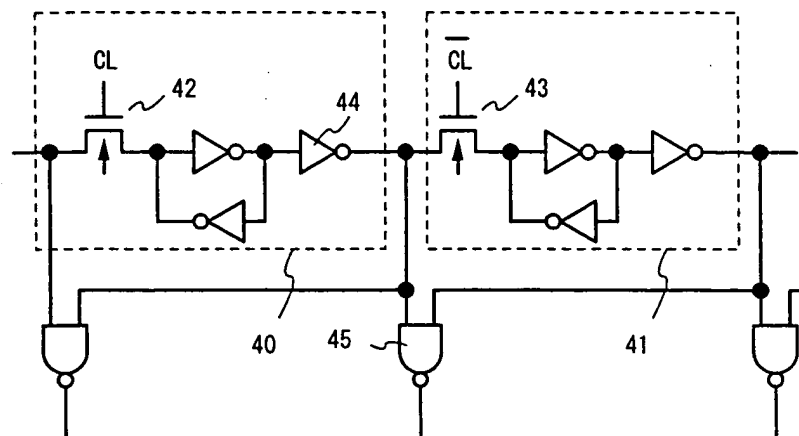


FIG. 8A

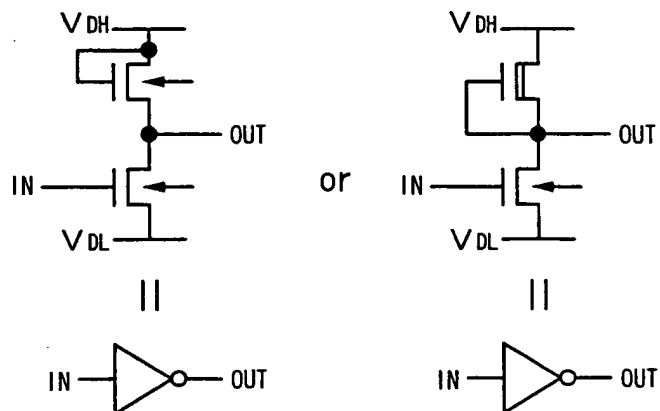


FIG. 8B

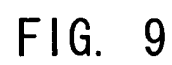


FIG. 9

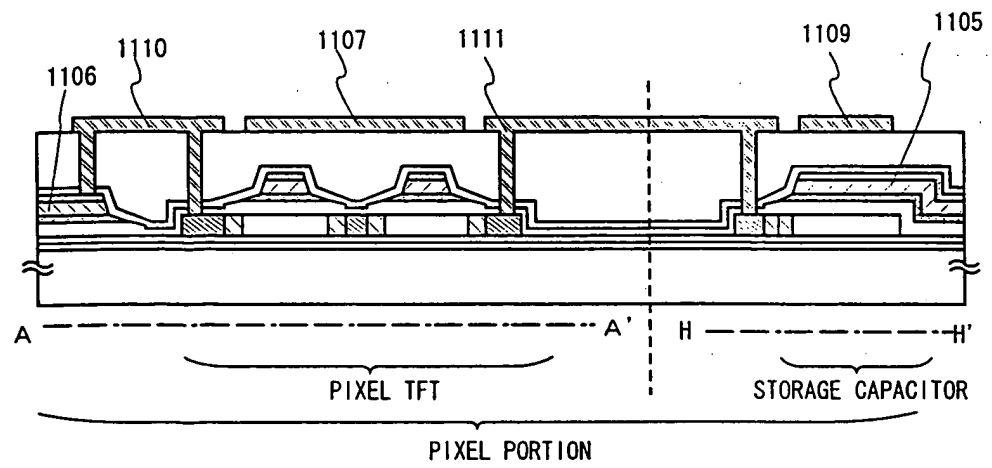
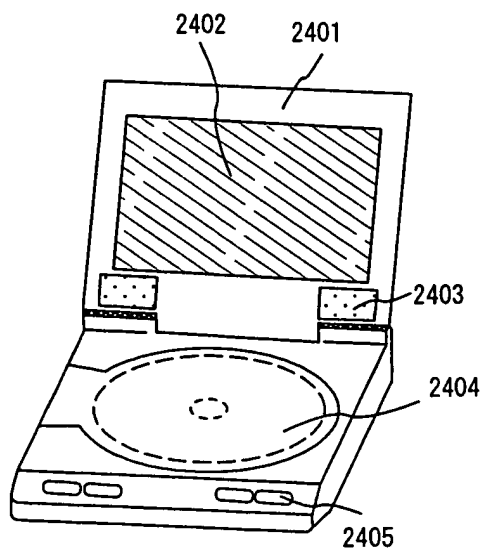
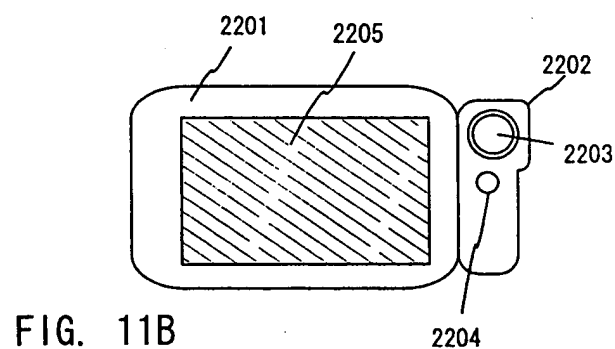
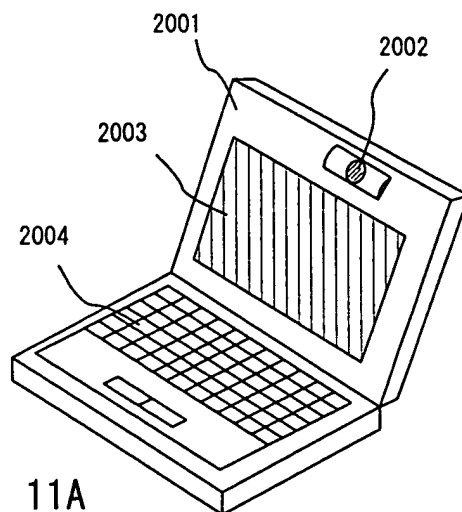


FIG. 10



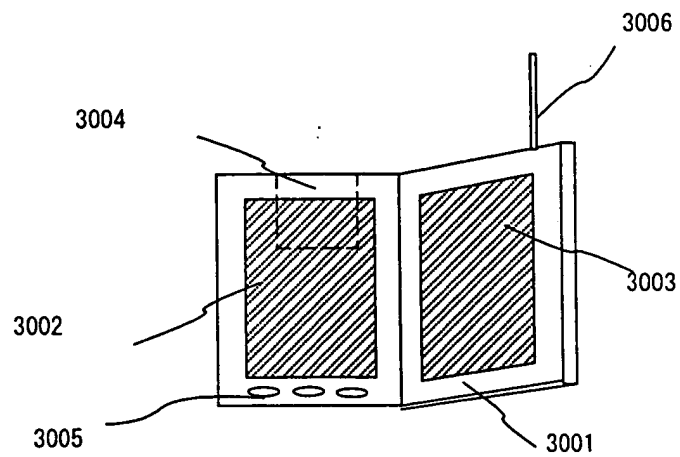


FIG. 12A

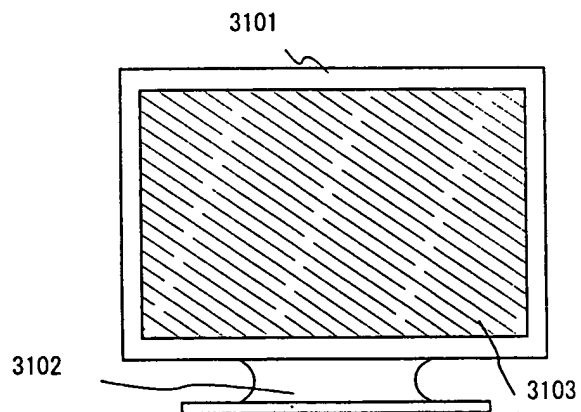


FIG. 12B

Applicant(s): Shunpei Yamazaki et al.

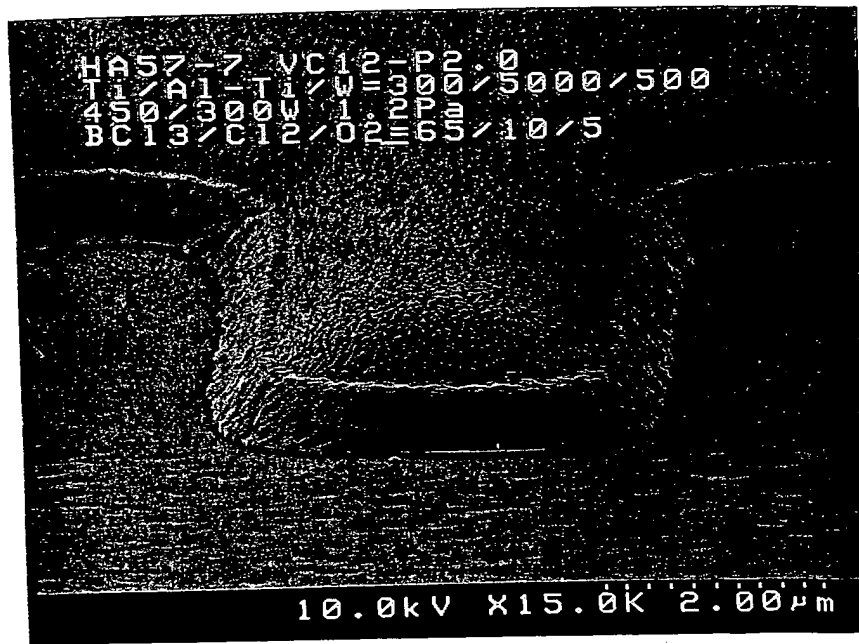
SEMICONDUCTOR DEVICE AND MANUFACTURING
METHOD THEREOF

FIG. 13

Applicant(s): Shunpei Yamazaki et al.

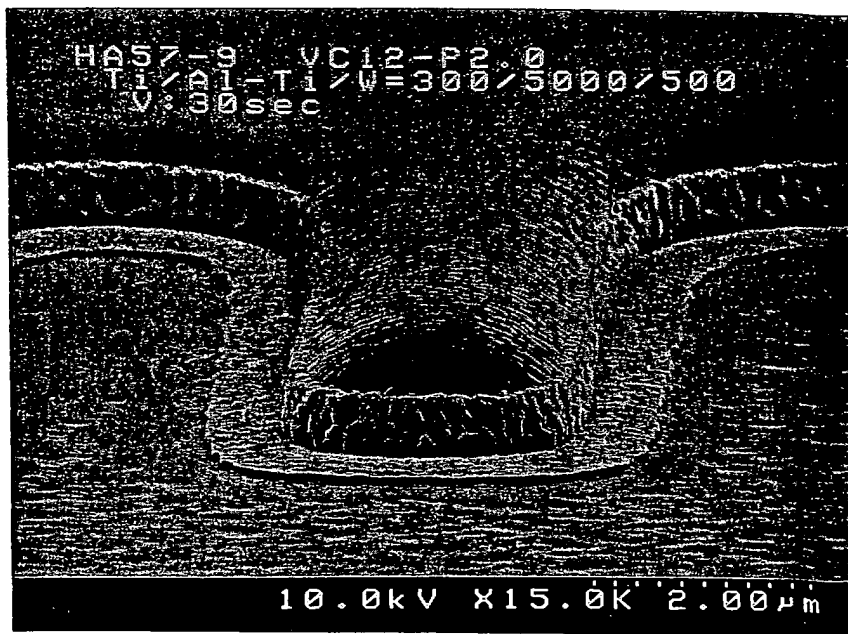
SEMICONDUCTOR DEVICE AND MANUFACTURING
METHOD THEREOF

FIG. 14

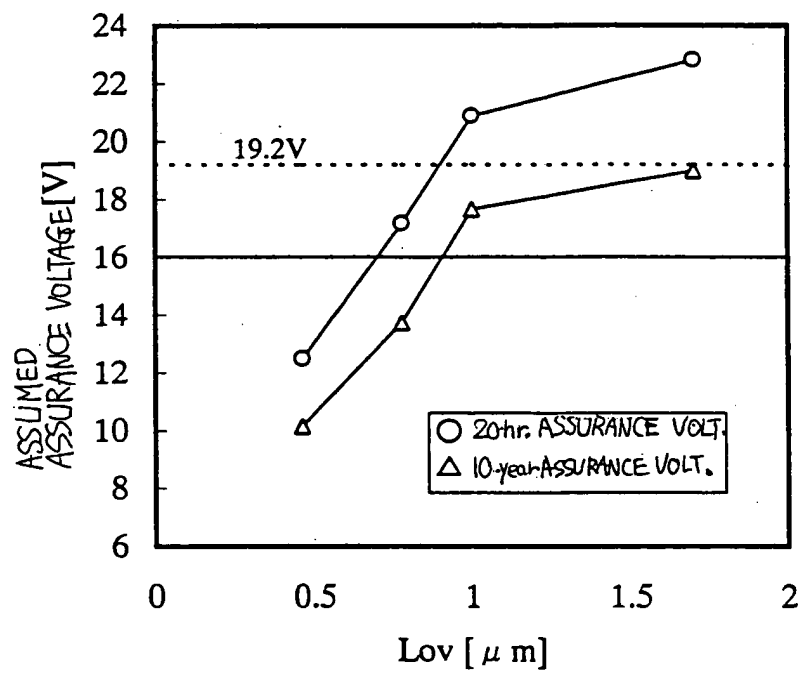


FIG. 15

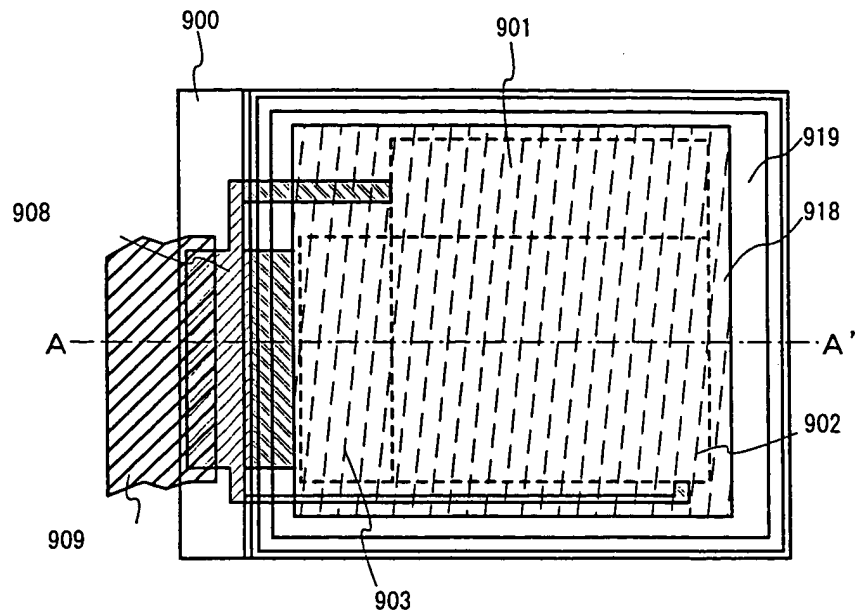


FIG. 16A

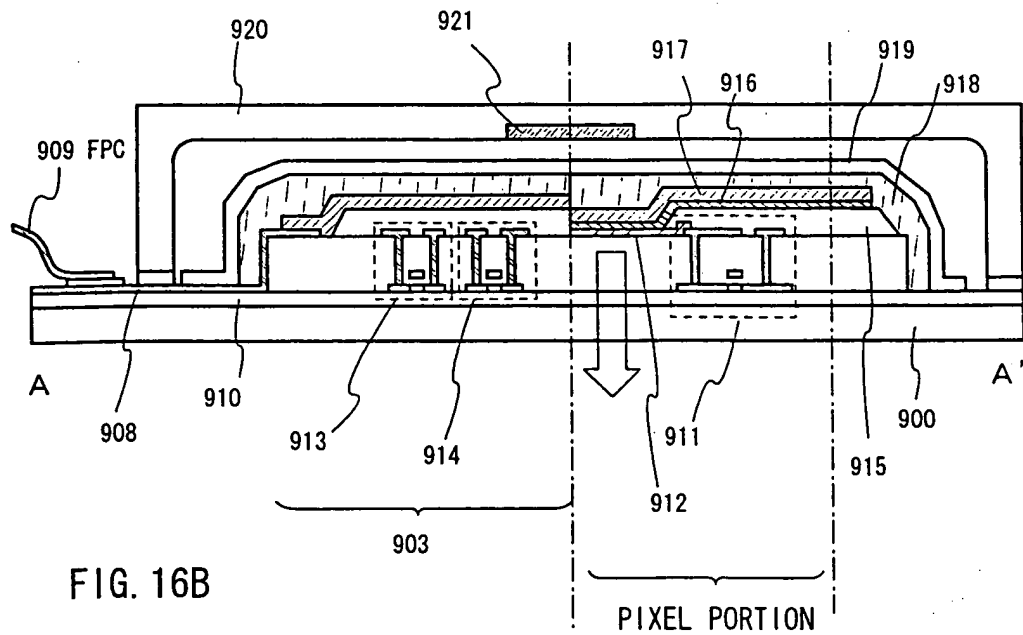


FIG. 16B

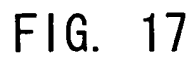
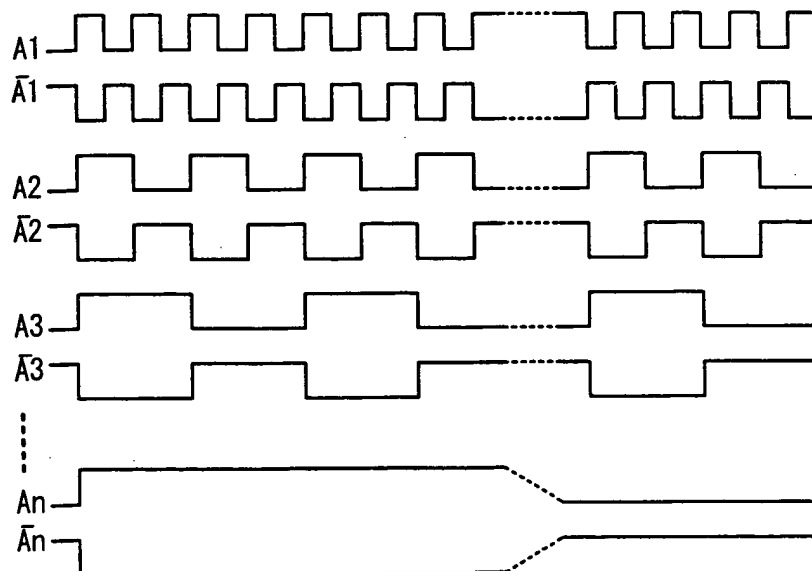
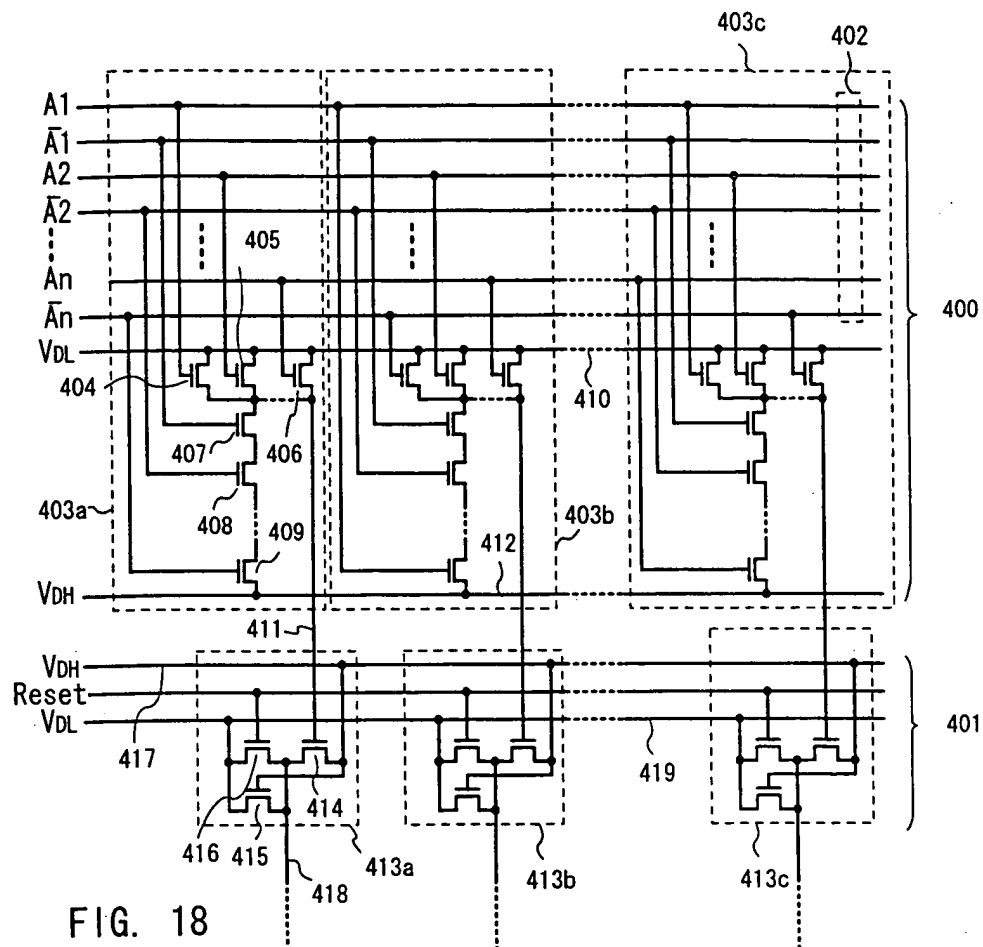


FIG. 17



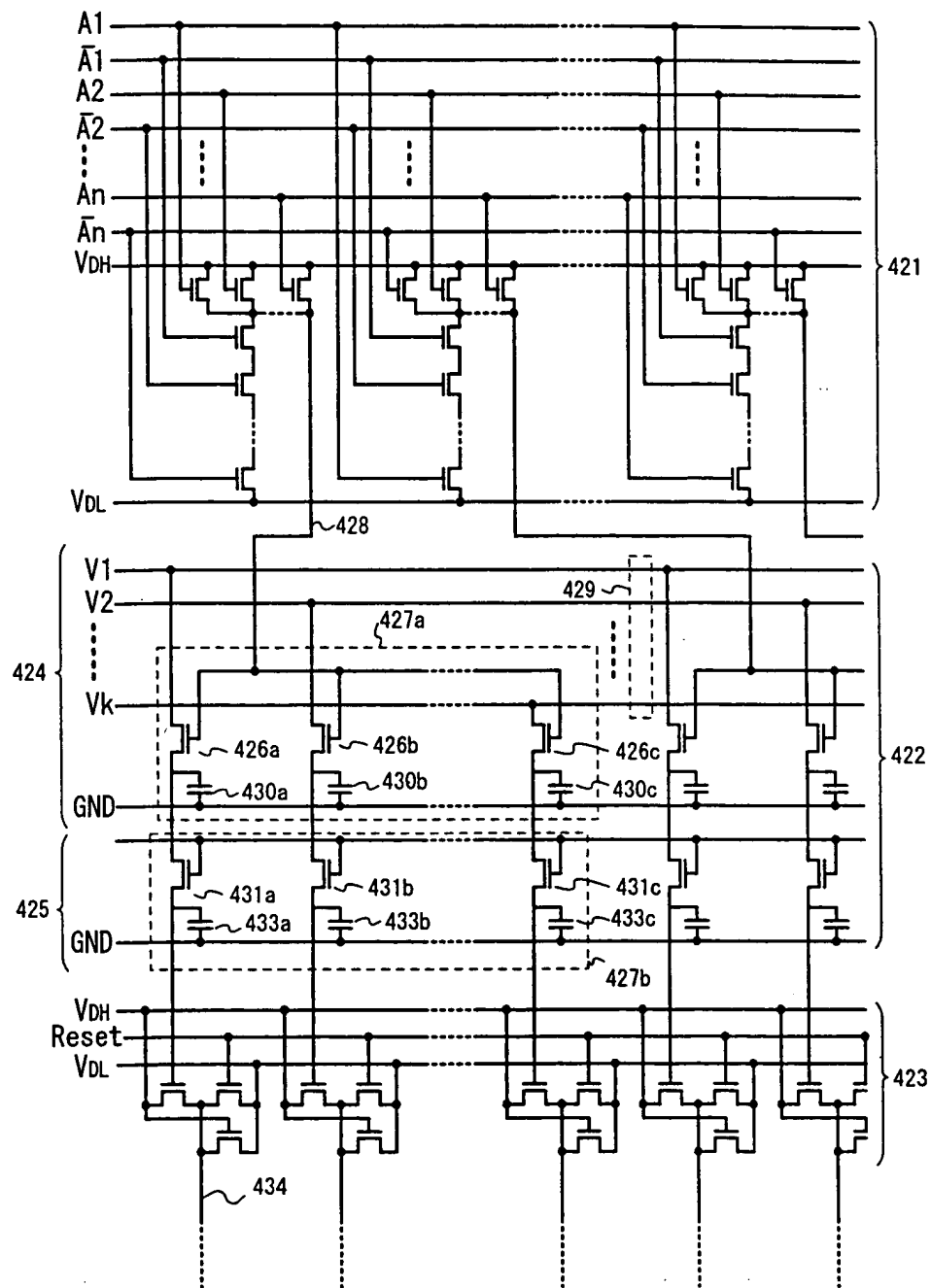


FIG. 20